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rfmd.com

RFSA2614

PARALLEL CONTROLLED DIGITAL STEP ATTENUATOR 50MHz TO 4000MHz, 6-BIT, 0.5dB

Package: QFN, 24-Pin, 4mm x 4mm



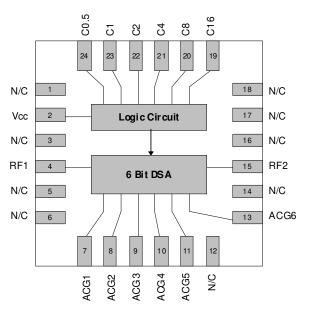


Features

- Frequency Range 50MHz to 4000MHz
- 6 Bits, 31.5dB Range, 0.5dB Step
- High Linearity, IIP3 >49dBm
- 3V and 5V Logic Compatible
- On-chip Parallel Decoder
- Parallel Programming Interface
- On-chip ESD Protection >500V HBM
- Single Supply, 3V to 5V Operation

Applications

- Transceiver RF and IF Applications
- Cellular, PCS, GSM, UMTS, LTE, WiMax/WiFi
- Wireless Data, Satellite Terminals
- Test Equipment



Functional Block Diagram

Product Description

The RFSA2614 is a 6-bit digital step attenuator (DSA) that features high linearity over the entire 31.5dB gain control range with excellent step accuracy in 0.5dB steps. The parallel-controlled RFSA2614 has an on-chip decoder that is both 3V and 5V compatible. It also offers a rugged Class 1B HBM ESD rating via on-chip ESD circuitry.

Ordering Information

RFSA2614SR 7" Reel with 100 pieces
RFSA2614SQ Sample bag with 25 pieces
RFSA2614TR7 7" Reel with 750 pieces
RFSA2614TR13 13" Reel with 2500 pieces

RFSA2614PCK-410 50MHz to 4000MHz PCBA with 5-piece sample bag

Optimum Technology Matching® Applied

☐ GaAs HBT	☐ SiGe BiCMOS	✓ GaAs pHEMT	☐ GaN HEMT
☐ GaAs MESFET	☐ Si BiCMOS	☐ Si CMOS	☐ BIFET HBT
☐ InGaP HBT	☐ SiGe HBT	☐ Si BJT	

RFSA2614



Absolute Maximum Ratings

Parameter	Rating	Unit
Supply Voltage	5.5	V _{DC}
DC Supply Current	15	mA
DC Power Dissipation	83	mW
Max RF Input Power	27	dBm
Operating Temperature (T _{CASE})	-40 to +85	°C
Storage Temperature	-40 to +150	°C
Junction Temperature	150	°C
ESD Rating (HBM)	Class 1B	
Moisture Sensitivity Level	MSL1	



Caution! ESD sensitive device.

Exceeding any one or a combination of the Absolute Maximum Rating conditions may cause permanent damage to the device. Extended application of Absolute Maximum Rating conditions to the device may reduce device reliability. Specified typical performance or functional operation of the device under Absolute Maximum Rating conditions is not implied.

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RFMD Green: RoHS compliant per EU Directive 2002/95/EC, halogen free per IEC 61249-2-21, < 1000 ppm each of antimony trioxide in polymeric materials and red phosphorus as a flame retardant, and <2% antimony in solder.

Davamatav	Specification		11	Oandition		
Parameter	Min.	Тур.	Max.	Unit	Condition	
Frequency Range	50		4000	MHz		
Insertion Loss		1.6	1.9	dB	500MHz, 0dB attenuation	
		1.7		dB	850MHz, 0dB attenuation	
		2.1		dB	2140MHz, OdB attenuation	
		2.2	2.8	dB	2700MHz, OdB attenuation	
		2.8		dB	3800MHz, OdB attenuation	
Gain Control Range		31.5		dB	0.5dB step size	
Step Accuracy	\pm (0.15 + 5.0% attenuation setting)		dB			
IIP3		>49		dBm	700MHz to 2700MHz, states 0 thru 27.5dB	
IIP3		>45		dBm	700MHz to 2700MHz, states 28 thru 31.5dB	
Input P1dB		>27		dBm	700MHz to 2700MHz, all states	
Return Loss		>18		dB	700MHz to 2700MHz, all states	
Control Interface		6		bit	Parallel interface	
Settling Time		200		ns	t _{RISE} , t _{FALL} (10%/90% RF)	
Switching Speed		200		ns	t _{ON} , t _{OFF} (50% CTL to 10%/90% RF)	
Supply Voltage (V _{DD})	3.0	5.0	5.25	V	Typical performance based on 5V opreation.	
Supply Current		3.5		mA		
Control Voltage (V _{CTL})	0		0.8	V	Low	
	2.0		V_{DD}	V	High	

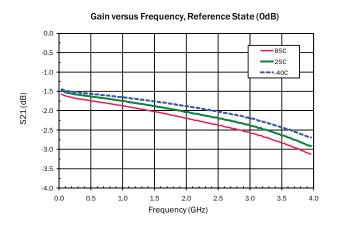
Notes:

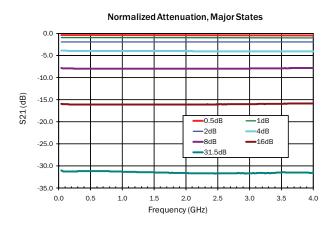
- 1. V_{DD} = 5V, V_{CTL} = 3V, T = 25 °C
- 2. Broadband Application Circuit (with ACG capacitors)
- 3. IIP3 measured with 1MHz spacing, P_{IN} = 4dBm/tone for frequency < 300MHz, P_{IN} = 10dBm/tone for frequency > 300MHz

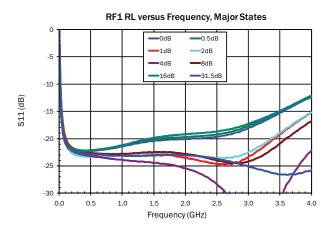


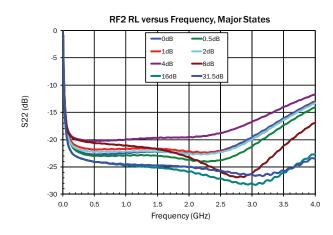
Typical Broadband Application Circuit Performance

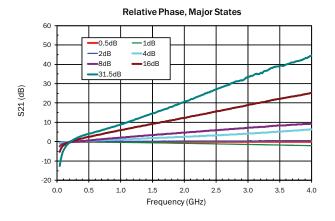
(with ACG capacitors)

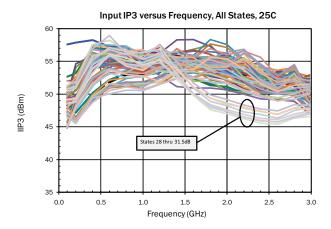








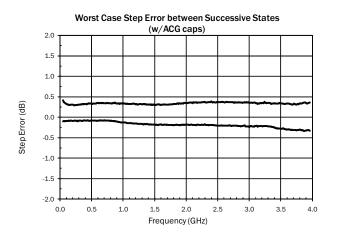




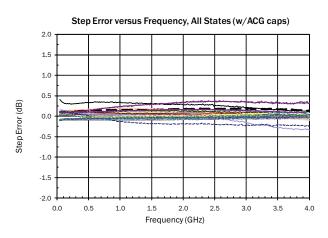


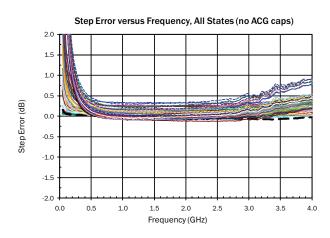
Typical Broadband Application Circuit Performance

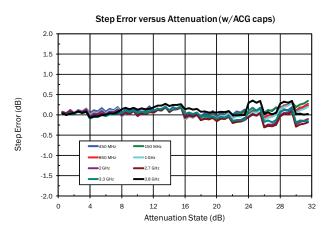
(with and without ACG capacitors)

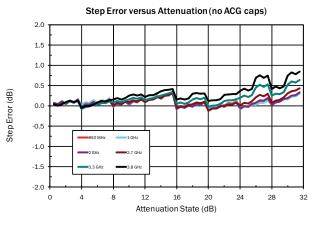
















Truth Table

Control Bit				Relative		
C16	C8	C4	C2	C1	C0.5	Gain Setting
1	1	1	1	1	1	Max gain
1	1	1	1	1	0	-0.5dB
1	1	1	1	0	1	-1dB
1	1	1	0	1	1	-2dB
1	1	0	1	1	1	-4dB
1	0	1	1	1	1	-8dB
0	1	1	1	1	1	-16dB
0	0	0	0	0	0	-31.5dB

Logic Voltage Levels			
State Logic			
Low	0V to 0.8V		
High	2.0V to 5.0V		

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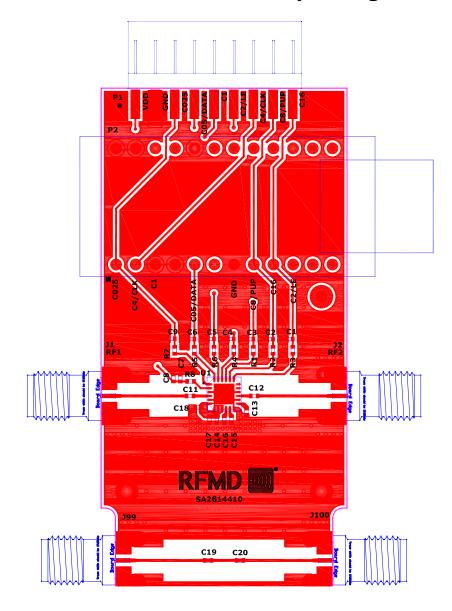


Pin Names and Descriptions

Pin	Name	Description
1	NC	No internal connection. EVB can be ground or no connect.
2	VDD	Power supply.
3	NC	No internal connection. EVB can be ground or no connect.
4	RF1	RF port. External DC block required.
5	NC	No internal connection. EVB can be ground or no connect.
6	NC	No internal connection. EVB can be ground or no connect.
7	ACG	AC ground connection for operation below 500MHz.
8	ACG	AC ground connection for operation below 500MHz.
9	ACG	AC ground connection for operation below 500MHz.
10	ACG	AC ground connection for operation below 500MHz.
11	ACG	AC ground connection for operation below 500MHz.
12	NC	No internal connection. EVB can be ground or no connect.
13	ACG	AC ground connection for operation below 500MHz.
14	NC	No internal connection. EVB can be ground or no connect.
15	RF2	RF port. External DC block required.
16	NC	No internal connection. EVB can be ground or no connect.
17	NC	No internal connection. EVB can be ground or no connect.
18	NC	No internal connection. EVB can be ground or no connect.
19	D5	16dB control bit.
20	D4	8dB control bit.
21	D3	4dB control bit.
22	D2	2dB control bit.
23	D1	1dB control bit.
24	D0	0.5dB control bit.
EPAD	GND	DC and RF ground. Must be soldered to EVB ground plane over a bed of vias for thermal and RF performance.



Evaluation Board Assembly Drawing

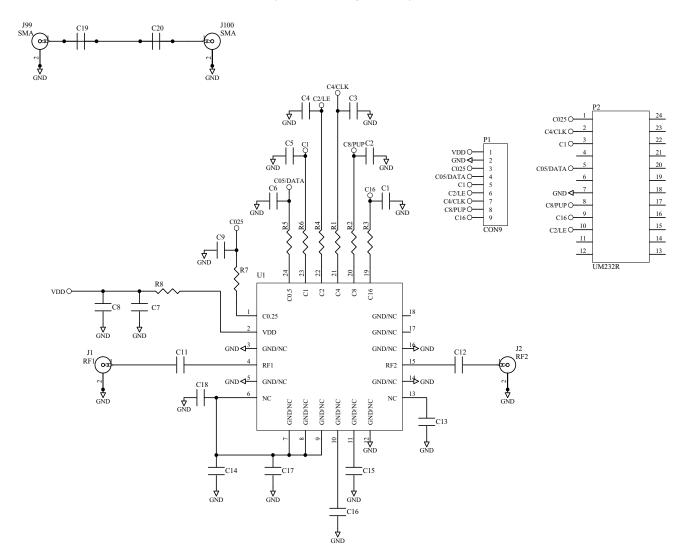


RFSA2614



Evaluation Board Schematic

(with ACG capacitors)



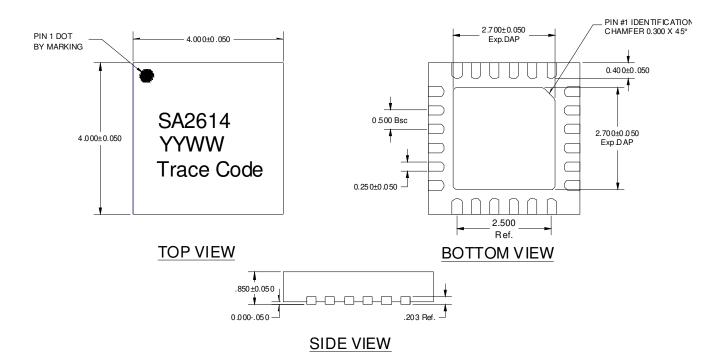


Evaluation Board Bill of Materials

Description	Reference Designator	Manufacturer	Manufacturer's P/N
RFSA2714 Evaluation Board	PCB itself	Dynamic Details (DDI) Toronto	SA2714410(A)
6-Bit SA Parallel 0.5dB QFN 4x4	U1	RFMD	RFSA2614SB
CAP, 680pF, 10%, 50V, X7R, 0402	C13, C15-C17	Murata Electronics N. America	GRM155R71H681KA01E
CAP, 1000pF, 10%, 50V, X7R, 0402	C7	Taiyo Yuden (USA), Inc.	RM UMK105BJ102KV-F
CAP, 470pF, 10%, 50V, X7R, 0402	C11-C12	Murata Electronics	GRM155R71H471KA01E
RES, 0Ω, 0402	R1-R6, R8	Kamaya, Inc	RMC1/16SJPTH
CONN, SMA, END LNCH, UNIV, HYB MNT, FLT	J1-J2, J99-J100	Molex	SD-73251-4000
CONN, HDR, ST, PLRZD, 9-PIN	P1	ITW Pancon	MPSS100-9-C
CONN, SKT, 24-PIN DIP, .600", T/H	P2	Aries Electronics Inc.	24-6518-10
MOD, USB TO SERIAL UART, SSOP-28	M1 (See Note Below)	Future Technology Devices Int'l	UM232R
DNP	C1-C6, C8-C9, C14, C18-C20, R7	NA	NA

Note: M1 should be mounted into P2 with respect to the Pin 1 alignment of M1 and P2

Package Drawing



YYWW = Date Code, where YY=year, WW=week
Trace Code to be assigned by assembly SubCon